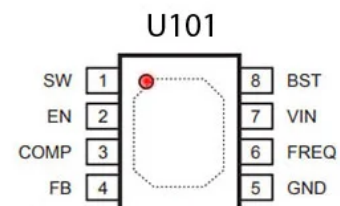
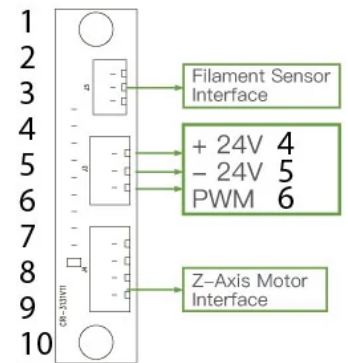
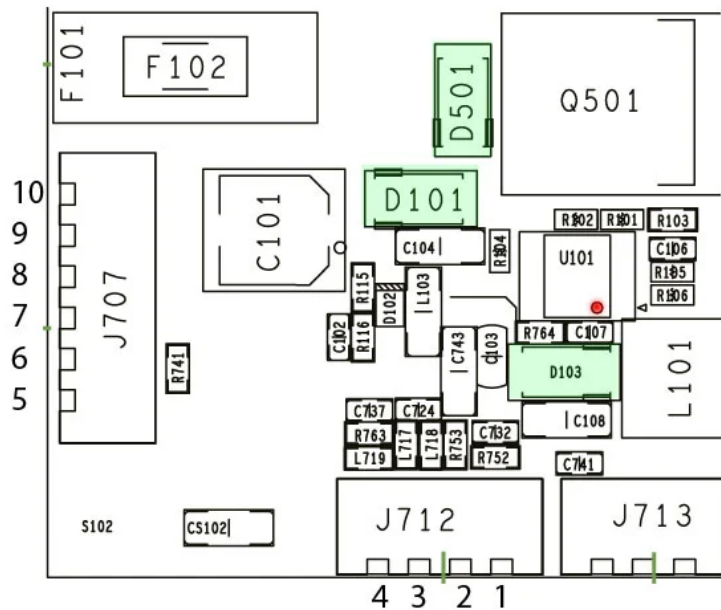
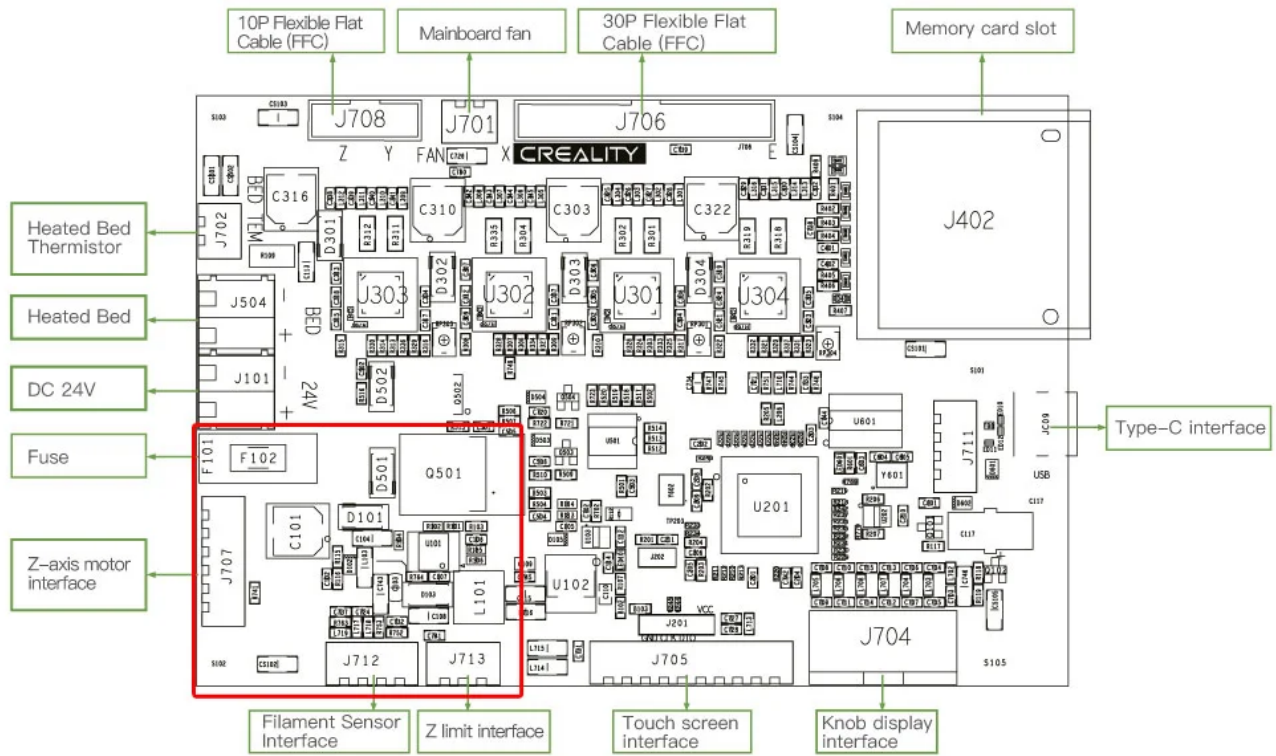


# Creality - Ender 3 S1/ Pro / Plus

- [Pinouts](#)

# Pinouts



SOIC Pin #	Name	Description
1	SW	Switch Node. This is the output from the high-side switch. A low forward drop Schottky diode to ground is required. The diode must be close to the SW pins to reduce switching spikes.
2	EN	Enable Input. Pulling this pin below the specified threshold shuts the chip down. Pulling it up above the specified threshold or leaving it floating enables the chip.
3	COMP	Compensation. This node is the output of the error amplifier. Control loop frequency compensation is applied to this pin.
4	FB	Feedback. This is the input to the error amplifier. The output voltage is set by a resistive divider connected between the output and GND which scales down $V_{OUT}$ equal to the internal +0.8V reference.
5	GND Exposed Pad	Ground. It should be connected as close as possible to the output capacitor to shorten the high current switch paths. Connect exposed pad to GND plane for optimal thermal performance.
6	FREQ	Switching Frequency Program Input. Connect a resistor from this pin to ground to set the switching frequency.
7	VIN	Input Supply. This supplies power to all the internal control circuitry, both BS regulators and the high-side switch. A decoupling capacitor to ground must be placed close to this pin to minimize switching spikes.
8	BST	Bootstrap. This is the positive power supply for the internal floating high-side MOSFET driver. Connect a bypass capacitor between this pin and SW pin.